

## **Marking Information**

Site 1



FP = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2016		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	D		Н	ı	J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2



FP = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2016	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	6	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	z

	Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Ī	Code	Т	U	V	W	X	Υ	Z



### **Maximum Ratings** (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	-20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±10	V		
Continuous Drain Current (Note 6) V 45V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	lo	-9.0 -7.2	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	lo	-11.1 -8.9	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			$I_{DM}$	-60	Α
Continuous Source-Drain Diode Current (Note 6)	Is	-2.4	Α		
Avalanche Current (Note 7) L = 0.1mH	las	-27	Α		
Avalanche Energy (Note 7) L = 0.1mH	E <sub>AS</sub>	38	mJ		

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	Pn	0.76	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	PD	0.48	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	р	165	°C/W	
Thermal Resistance, Junction to Ambient (Note 3)	t<10s	$R_{\theta JA}$	116		
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	D-	1.90	W	
Total Power Dissipation (Note 6)	$T_A = +70$ °C	PD	1.20		
Thermal Peciatones, Junction to Ambient (Note 6)	Steady state	D	67		
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	RθJA	47	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Steady state	Rejc	18		
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

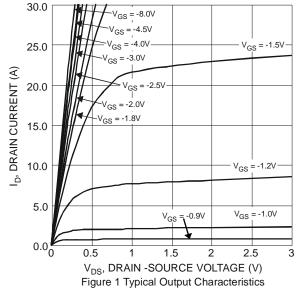
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

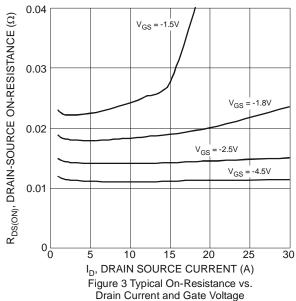
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)		•				•
Drain-Source Breakdown Voltage	BVDSS	-20	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	IDSS	_	_	-1	μA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	Igss	_	_	±10	μA	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	Vgs(th)	-0.35	_	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$
			12	16		$V_{GS} = -4.5V, I_{D} = -7.0A$
Static Drain-Source On-Resistance	Pro/out		15	22	mΩ	$V_{GS} = -2.5V, I_{D} = -5.0A$
Static Diain-Source On-Nesistance	RDS(ON)	_	19	40	11152	$V_{GS} = -1.8V, I_{D} = -3.0A$
			21	80		$V_{GS} = -1.5V, I_D = -1.0A$
Diode Forward Voltage	VsD	_	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -1.0A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	2,760	_		15// 1/ 0//
Output Capacitance	Coss	_	262	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	Crss		220	_		1 = 1.000112
Gate Resistance	Rg	_	16	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	34	_		
Total Gate Charge (VGS = -8V)	Qg	_	59	_	nC	Vps = -15V. lp = -4.0A
Gate-Source Charge	Qgs	_	3.5	_	IIC	VDS = -15V, ID = -4.0A
Gate-Drain Charge	Qgd	_	8.3	_		
Turn-On Delay Time	tD(ON)	_	7.5	_		
Turn-On Rise Time	t <sub>R</sub>	_	25	_		$V_{DS} = -15V$ , $V_{GS} = -4.5V$ ,
Turn-Off Delay Time	tD(OFF)		125		ns	$R_G = 1\Omega$ , $I_D = -4.0A$
Turn-Off Fall Time	tF	_	96	_		
Reverse Recovery Time	t <sub>RR</sub>	_	48	_	ns	I <sub>F</sub> = -1.0A, di/dt = 100A/µs
Reverse Recovery Charge	Qrr	_	33	_	nC	IF = -1.0A, di/dt = 100A/µs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.

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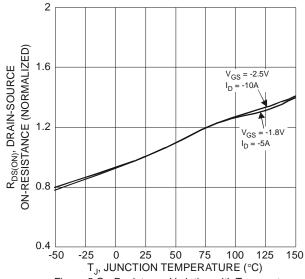
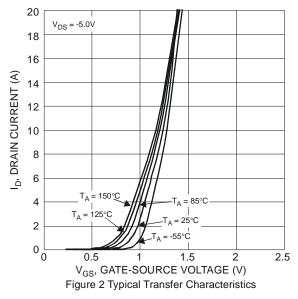
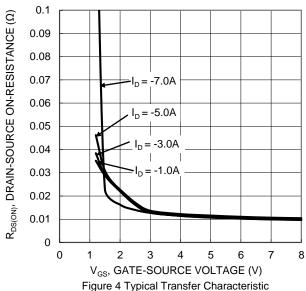


Figure 5 On-Resistance Variation with Temperature





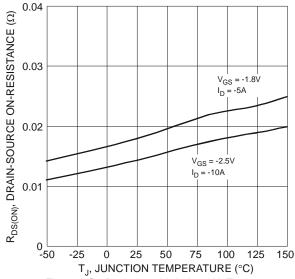


Figure 6 On-Resistance Variation with Temperature

# DMP2021UFDE



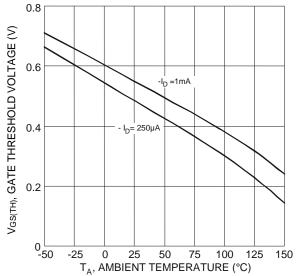
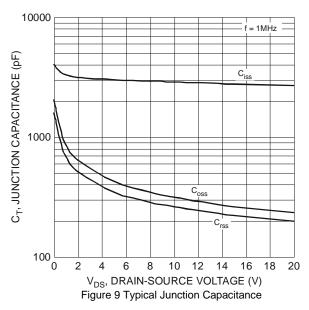
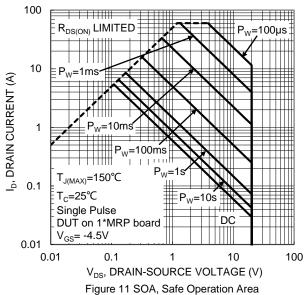
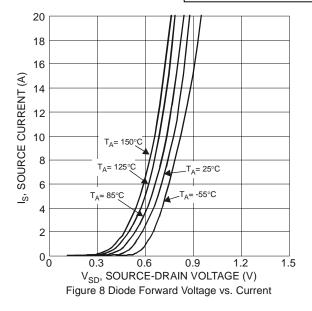
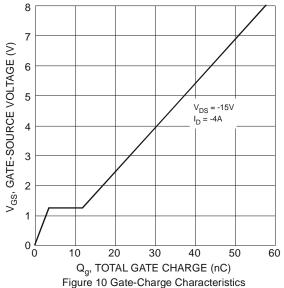


Figure 7 Gate Threshold Variation vs. Ambient Temperature











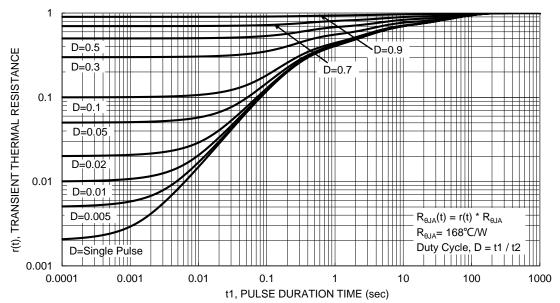


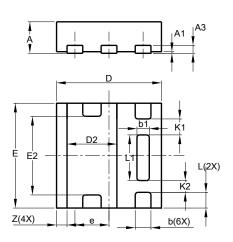
Figure 12 Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type E)

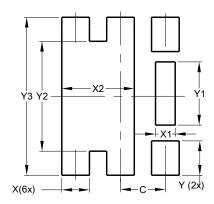


U-DFN2020-6								
Type E								
Dim	Min	Max	Тур					
Α	0.57	0.63	0.60					
A1	0	0.05	0.03					
A3	ı	1	0.15					
b	0.25	0.35	0.30					
b1	0.185	0.285	0.235					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
Е	1.95	2.05	2.00					
E2	1.40	1.60	1.50					
е	_	-	0.65					
L	0.25	0.35	0.30					
L1	0.82	0.92	0.87					
K1	_	-	0.305					
K2	_	_	0.225					
Z	-	_	0.20					
All	Dimen	sions i	n mm					

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type E)



Dimensions	Value (in mm)				
С	0.650				
X	0.400				
X1	0.285				
X2	1.050				
Y	0.500				
Y1	0.920				
Y2	1.600				
Y3	2.300				



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